

# Junghyun Cho

## List of Publications by Year in descending order

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74  
papers

1,413  
citations

331670

21  
h-index

361022

35  
g-index

74  
all docs

74  
docs citations

74  
times ranked

1240  
citing authors

#	ARTICLE	IF	CITATIONS
1	Effect of Yttrium and Lanthanum on the Tensile Creep Behavior of Aluminum Oxide. <i>Journal of the American Ceramic Society</i> , 1997, 80, 1013-1017.	3.8	183
2	Role of segregating dopants on the improved creep resistance of aluminum oxide. <i>Acta Materialia</i> , 1999, 47, 4197-4207.	7.9	141
3	Photocatalytic TiO <sub>2</sub> nanomaterials as potential antimicrobial and antiviral agents: Scope against blocking the SARS-COV-2 spread. <i>Micro and Nano Engineering</i> , 2022, 14, 100100.	2.9	77
4	Hydrothermal synthesis of TiO <sub>2</sub> nanorods: formation chemistry, growth mechanism, and tailoring of surface properties for photocatalytic activities. <i>Materials Today Chemistry</i> , 2021, 20, 100428.	3.5	65
5	Evaluation of Die Stress in MEMS Packaging: Experimental and Theoretical Approaches. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2006, 29, 735-742.	1.3	62
6	Atomic structural environment of grain boundary segregated Y and Zr in creep resistant alumina from EXAFS. <i>Acta Materialia</i> , 1999, 47, 3411-3422.	7.9	55
7	TiO <sub>2</sub> nanoflower photocatalysts: Synthesis, modifications and applications in wastewater treatment for removal of emerging organic pollutants. <i>Environmental Research</i> , 2022, 212, 113550.	7.5	47
8	Scanning Transmission Electron Microscopy Analysis of Grain Boundaries in Creep-Resistant Yttrium- and Lanthanum-Doped Alumina Microstructures. <i>Journal of the American Ceramic Society</i> , 1999, 82, 2865-2870.	3.8	45
9	Influence of Yttrium Doping on Grain Misorientation in Aluminum Oxide. <i>Journal of the American Ceramic Society</i> , 1998, 81, 3001-3004.	3.8	43
10	Enhanced mechanical properties of polyurethane composite coatings through nanosilica addition. <i>Progress in Organic Coatings</i> , 2016, 90, 243-251.	3.9	43
11	A kinetic Monte Carlo simulation of film growth by physical vapor deposition on rotating substrates. <i>Materials Science &amp; Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2005, 391, 390-401.	5.6	42
12	Effect of Oxidation on Indium Solderability. <i>Journal of Electronic Materials</i> , 2008, 37, 483-489.	2.2	41
13	Microstructure Evolution and the Constitutive Relations of High-Temperature Solders. <i>Journal of Electronic Materials</i> , 2009, 38, 802-809.	2.2	35
14	Oxidation and reduction behavior of pure indium. <i>Journal of Materials Research</i> , 2009, 24, 386-393.	2.6	32
15	Buckling and Ferromagnetism of Aligned Cr-Doped ZnO Nanorods. <i>Journal of Physical Chemistry C</i> , 2008, 112, 19236-19241.	3.1	31
16	Effects of curing conditions on structural evolution and mechanical properties of UV-curable polyurethane acrylate coatings. <i>Progress in Organic Coatings</i> , 2018, 114, 58-67.	3.9	30
17	Improved tensile creep properties of yttrium- and lanthanum-doped alumina: a solid solution effect. <i>Journal of Materials Research</i> , 2001, 16, 425-429.	2.6	29
18	Titanium Oxide Nanoparticles Precipitated from Low-Temperature Aqueous Solutions: I. Nucleation, Growth, and Aggregation. <i>Journal of the American Ceramic Society</i> , 2008, 91, 3875-3882.	3.8	28

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19	Modeling of Grain-Grain Boundary Segregation Behavior in Aluminum Oxide. <i>Journal of the American Ceramic Society</i> , 2000, 83, 344-352.	3.8	22
20	Low temperature processed SnO <sub>2</sub> films using aqueous precursor solutions. <i>Ceramics International</i> , 2013, 39, 143-151.	4.8	22
21	Mineralization of flagella for nanotube formation. <i>Materials Science and Engineering C</i> , 2009, 29, 2282-2286.	7.3	21
22	A biomimetic approach to the deposition of ZrO <sub>2</sub> films on self-assembled nanoscale templates. <i>Materials Science and Engineering C</i> , 2006, 26, 1344-1350.	7.3	18
23	Enhancing the oxidation resistance of copper by using sandblasted copper surfaces. <i>Applied Surface Science</i> , 2015, 357, 2160-2168.	6.1	18
24	Improved adhesion of polyurethane-based nanocomposite coatings to tin surface through silane coupling agents. <i>International Journal of Adhesion and Adhesives</i> , 2021, 110, 102948.	2.9	17
25	Effect of alloying elements on the creep behavior of high Pb-based solders. <i>Materials Science &amp; Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2011, 528, 1063-1070.	5.6	15
26	Titanium Oxide Nanoparticles Precipitated from Low-Temperature Aqueous Solutions: III. Thin Film Properties. <i>Journal of the American Ceramic Society</i> , 2012, 95, 676-683.	3.8	13
27	Electron beam irradiation effect on the mechanical properties of nanosilica-filled polyurethane films. <i>Polymer Degradation and Stability</i> , 2017, 141, 45-53.	5.8	13
28	Hydrothermally-grown nanostructured anatase TiO <sub>2</sub> coatings tailored for photocatalytic and antibacterial properties. <i>Ceramics International</i> , 2019, 45, 23216-23224.	4.8	13
29	Strong P-band emission and third harmonic generation from ZnO nanorods. <i>Solid State Communications</i> , 2012, 152, 1241-1243.	1.9	12
30	Microstructure developments of F-doped SiO <sub>2</sub> thin films prepared by liquid phase deposition. <i>Thin Solid Films</i> , 2012, 520, 1718-1723.	1.8	11
31	Improved adhesion of polyurethane-based coatings to tin surface. <i>Journal of Materials Science: Materials in Electronics</i> , 2019, 30, 7268-7279.	2.2	11
32	Microstructure and mechanical properties of ceramic/self-assembled monolayer bilayer coatings. <i>Journal of Electronic Materials</i> , 2005, 34, 528-533.	2.2	10
33	Growth kinetics of bismuth nickel intermetallics. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 19034-19042.	2.2	10
34	Development of Conformal PDMS and Parylene Coatings for Microelectronics and MEMS Packaging. , 2005, , 279.		9
35	Titanium Oxide Nanoparticles Precipitated from Low-Temperature Aqueous Solutions: II. Thin Film Formation and Microstructure Developments. <i>Journal of the American Ceramic Society</i> , 2010, 93, 1909-1915.	3.8	9
36	Bismuth-Based Transient Liquid Phase (TLP) Bonding as High-Temperature Lead-Free Solder Alternatives. , 2017, , .		9

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37	Effective charge collection area during conductive and photoconductive atomic force microscopy. Applied Physics Letters, 2018, 112, .	3.3	9
38	Effect of coating adhesion and degradation on tin whisker mitigation of polyurethane-based conformal coatings. Polymer Degradation and Stability, 2019, 166, 219-229.	5.8	9
39	Electrodeposition of Titania Thin Films on Metallic Surface for High Dielectric Applications. Journal of the American Ceramic Society, 2010, 93, 774-781.	3.8	8
40	Dielectric Properties of Solution-Deposited Crystalline Barium Titanate Thin Films. Journal of the American Ceramic Society, 2012, 95, 1189-1192.	3.8	8
41	Developments of high-Bi alloys as a high temperature Pb-free solder. , 2014, , .		8
42	Toward a better understanding of synthesis and processing of ceramic/self-assembled monolayer bilayer coatings. Journal of Electronic Materials, 2005, 34, 534-540.	2.2	7
43	Ultrahigh photosensitivity of the polar surfaces of single crystalline ZnO nanoplates. Nanoscale, 2018, 10, 6801-6805.	5.6	7
44	Lead-Free Alternatives for Interconnects in High-Temperature Electronics. Journal of Electronic Packaging, Transactions of the ASME, 2018, 140, .	1.8	7
45	Microstructure development of hydrothermally grown TiO <sub>2</sub> thin films with vertically aligned nanorods. Journal of the American Ceramic Society, 2018, 101, 50-60.	3.8	6
46	Exploring Bismuth as a New Pb-Free Alternative for High Temperature Electronics. , 2016, , .		5
47	Aging Studies of Cu-Sn Intermetallics in Cu Micropillars Used in Flip Chip Attachment onto Cu Lead Frames. Journal of Electronic Materials, 2018, 47, 1694-1704.	2.2	5
48	Nanoscale Insight into Performance Loss Mechanisms in P3HT:ZnO Nanorod Solar Cells. ACS Applied Energy Materials, 2018, 1, 6172-6180.	5.1	5
49	Effects of bismuth and nickel on the microstructure evolution of Sn-Ag-Cu (SAC)-based solders. Materials Today Communications, 2021, 26, 101787.	1.9	5
50	Effects of Microstructure Evolution on High-Temperature Mechanical Deformation of 95Sn-5Sb. , 2008, , .		4
51	Properties of Liquid-Phase Deposited Silica Films for Low Dielectric Applications. Journal of the American Ceramic Society, 2009, 92, 2388-2391.	3.8	4
52	Developments of Bi-Sb-Cu alloys as a high-temperature Pb-free solder. , 2015, , .		4
53	Hierarchical Organization of TiO <sub>2</sub> Nanostructures in Low-Temperature Solution Processes. Journal of the American Ceramic Society, 2016, 99, 431-439.	3.8	4
54	Tailoring of Stress Development in MEMS Packaging Systems. Materials Research Society Symposia Proceedings, 2002, 741, 5221.	0.1	3

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55	Vertically Aligned ZnO Nanorods Grown by Low-Temperature Solution Processing. Japanese Journal of Applied Physics, 2013, 52, 05DA09.	1.5	3
56	Superplasticity from viscous flow in high Pb ternary alloy. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2016, 658, 210-220.	5.6	3
57	Long-term thermal aging of parylene conformal coating under high humidity and its effects on tin whisker mitigation. Polymer Degradation and Stability, 2021, 191, 109667.	5.8	3
58	Developments of Low-Temperature Solution Processing for Nanostructured Titania Dielectric Films. Science of Advanced Materials, 2010, 2, 90-101.	0.7	3
59	A Nanoindentation Study of Thermally-Grown-Oxide Films on Silicon. Materials Research Society Symposia Proceedings, 2004, 841, R12.10.1.	0.1	2
60	Constitutive Relations of High Temperature Solders. , 2007, , 201.		2
61	Inorganic-Organic Barrier Coatings for Flexible OLED Applications. , 2008, , .		2
62	Parylene-PDMS Bilayer Coatings for Microelectronic and MEMS Packaging. Materials Research Society Symposia Proceedings, 2006, 968, 1.	0.1	1
63	Thermodynamics and Kinetics of Oxidation of Pure Indium Solders. Materials Research Society Symposia Proceedings, 2006, 968, 1.	0.1	1
64	Effects of the Interlayer Thickness and Alloying on the Reliability of Transient Liquid Phase (TLP) Bonding. , 2018, , .		1
65	Structural Evolution and Mechanical Behavior of Bio-inspired Oxide Films on Self-Assembled Organic Layers. Materials Research Society Symposia Proceedings, 2006, 975, 1.	0.1	1
66	Influence of Second Phase Particles on Thermal Conductivity of Bi Alloys. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 502-511.	2.5	1
67	Development of Protective Coatings for Silicon Devices. , 2003, , 373.		0
68	Mechanical Behavior of Ceramic/SAM Bilayer Coatings. Materials Research Society Symposia Proceedings, 2004, 844, 1.	0.1	0
69	Nanostructured Ceramic Film Formation on Self-Assembled Monolayers via a Biomimetic Approach. Materials Research Society Symposia Proceedings, 2005, 901, 1.	0.1	0
70	Protection From Oxygen and Moisture Via Thin Oxide Barrier Coating for Organic Electronics. , 2007, , 209.		0
71	Aligned Carbon Nanotube Polymer Composites. , 2007, , .		0
72	Polyimide Flex Circuitry for >200C. , 0, , .		0

#	ARTICLE	IF	CITATIONS
73	Process Developments in Transient Liquid Phase Bonding of Bi-Ni for High-Temperature Pb-Free Solder Alternatives. , 2021, , .		0
74	Metallurgical Aspects of Wire Bonds. , 2019, , 179-204.		0